

Title (en)  
FLUX FOR SOLDER PASTE AND SOLDER PASTE

Title (de)  
FLUSSMITTEL FÜR EINE LÖTPASTE UND LÖTPASTE

Title (fr)  
FLUX POUR PÂTE À SOUDER ET PÂTE À SOUDER

Publication  
**EP 3804902 A4 20220316 (EN)**

Application  
**EP 19811838 A 20190528**

Priority  
• JP 2018106468 A 20180601  
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Abstract (en)  
[origin: EP3804902A1] Provided are: a flux that is for a solder paste and that can inhibit occurrence of voids; and a solder paste using the flux. This flux for a solder paste contains rosin, an imidazole compound, and a solvent, wherein the contained amount of the imidazole compound is 25-35 mass%. The flux also contains 0-20 mass% of a block organic acid and 0-3 mass% of an activator.

IPC 8 full level  
**B23K 35/363** (2006.01); **B23K 35/02** (2006.01); **B23K 35/26** (2006.01); **B23K 35/36** (2006.01); **B23K 35/362** (2006.01); **C22C 13/00** (2006.01); **C22C 13/02** (2006.01)

CPC (source: EP KR US)  
**B23K 35/025** (2013.01 - EP US); **B23K 35/26** (2013.01 - KR); **B23K 35/262** (2013.01 - EP US); **B23K 35/3612** (2013.01 - EP); **B23K 35/3613** (2013.01 - US); **B23K 35/3616** (2013.01 - KR); **B23K 35/362** (2013.01 - EP US); **C22C 13/00** (2013.01 - EP KR US); **C22C 13/02** (2013.01 - EP)

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Designated contracting state (EPC)  
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MX 2020012706 A 20220131; MY 185259 A 20210430; PH 12020552043 A1 20210607; RS 64194 B1 20230630; TW 202016220 A 20200501;  
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MX 2020012706 A 20190528; MY PI2020006236 A 20190528; PH 12020552043 A 20201127; RS P20230362 A 20190528;  
TW 108118707 A 20190530; US 201917059435 A 20190528